

ULTEM™ RESIN 1010TC

DESCRIPTION

ULTEM 1010TC Resin is an unreinforced amorphous polyetherimide (PEI) resin that may offer a high glass transition temperature (Tg) of 217°C and improved flow. Features are controlled light transmission levels (different colors for different transmission%) and offer excellent mechanical, electrical and dimensional properties up to high temperatures. The material may offer very good chemical resistance for an amorphous material and is inherently flame retardant offering UL94 V0 and 5V ratings. The material is RoHS compliant and the natural.

GENERAL INFORMATION	
Features	Flame Retardant, Chemical Resistance, Good Processability, High Flow, Hydrolytic Stability, Low Smoke and Toxicity, Thin Wall, Dielectrics, Amorphous, Low Shrinkage, IR Transparent, Transparent/Translucent, Non halogenated flame retardant, Electroplatable, Creep resistant, Dimensional stability, High stiffness/Strength, High temperature resistance, No PFAS intentionally added
Fillers	Unreinforced
Polymer Types	Polyetherimide (PEI)
Processing Techniques	Film Extrusion, Injection Molding, Extrusion, Compression molding, Injection compression molding
Regional Availability	Asia

INDUSTRY	SUB INDUSTRY
Consumer	Personal Accessory
Electrical and Electronics	Mobile Phone - Computer - Tablets, Speaker - Earphone, Wireless Communication

TYPICAL PROPERTY VALUES

Revision 20230607

PROPERTIES	TYPICAL VALUES	UNITS	TEST METHODS
MECHANICAL ⁽¹⁾			
Tensile Stress, yield, 50 mm/min	110	MPa	ISO 527
Tensile Strain, yield, 50 mm/min	6	%	ISO 527
Tensile Strain, break, 50 mm/min	50	%	ISO 527
Tensile Modulus, 1 mm/min	3200	MPa	ISO 527
Flexural Stress, yield, 2 mm/min	160	MPa	ISO 178
Flexural Modulus, 2 mm/min	3300	MPa	ISO 178
Ball Indentation Hardness, H358/30	140	MPa	ISO 2039-1
Hardness, Rockwell M	106	-	ISO 2039-2
Tensile Stress, yld, Type I, 50 mm/min	115	MPa	ASTM D638
Tensile Strain, yld, Type I, 50 mm/min	7	%	ASTM D638
Tensile Strain, brk, Type I, 50 mm/min	60	%	ASTM D638
Tensile Stress, yld, Type I, 5 mm/min	110	MPa	ASTM D638
Tensile Strain, yld, Type I, 5 mm/min	7	%	ASTM D638
Tensile Strain, brk, Type I, 5 mm/min	60	%	ASTM D638
Tensile Modulus, 5 mm/min	3350	MPa	ASTM D638
Flexural Stress, yld, 1.3 mm/min, 50 mm span	165	MPa	ASTM D790
Flexural Modulus, 1.3 mm/min, 50 mm span	3200	MPa	ASTM D790
Flexural Stress, yld, 2.6 mm/min, 100 mm span	160	MPa	ASTM D790
Flexural Modulus, 2.6 mm/min, 100 mm span	3400	MPa	ASTM D790

PROPERTIES	TYPICAL VALUES	UNITS	TEST METHODS
Hardness, Rockwell M	109	-	ASTM D785
Taber Abrasion, CS-17, 1 kg	10	mg/1000cy	ASTM D1044
IMPACT ⁽¹⁾			
Izod Impact, unnotched 80*10*4 +23°C	NB	kJ/m ²	ISO 180/1U
Izod Impact, unnotched 80*10*4 -30°C	NB	kJ/m ²	ISO 180/1U
Izod Impact, notched 80*10*4 +23°C	5	kJ/m ²	ISO 180/1A
Izod Impact, notched 80*10*4 -30°C	5	kJ/m ²	ISO 180/1A
Charpy 23°C, V-notch Edgew 80*10*4 sp=62mm	4	kJ/m ²	ISO 179/1eA
Charpy -30°C, V-notch Edgew 80*10*4 sp=62mm	4	kJ/m ²	ISO 179/1eA
Izod Impact, unnotched, 23°C	1600	J/m	ASTM D4812
Izod Impact, unnotched, -30°C	1500	J/m	ASTM D4812
Izod Impact, notched, 23°C	32	J/m	ASTM D256
Izod Impact, notched, -30°C	41	J/m	ASTM D256
Izod Impact, Reverse Notched, 3.2 mm	1174	J/m	ASTM D256
Gardner, 23°C	33	J	SABIC method
THERMAL ⁽¹⁾			
HDT/Bf, 0.45 MPa Flatw 80*10*4 sp=64mm	209	°C	ISO 75/Bf
HDT/Af, 1.8 MPa Flatw 80*10*4 sp=64mm	192	°C	ISO 75/Af
Vicat Softening Temp, Rate A/50	215	°C	ISO 306
Vicat Softening Temp, Rate B/50	211	°C	ISO 306
Vicat Softening Temp, Rate B/120	212	°C	ISO 306
CTE, -40°C to 150°C, flow	5.2E-05	1/°C	ISO 11359-2
CTE, -40°C to 150°C, xflow	5.2E-05	1/°C	ISO 11359-2
Ball Pressure Test, 125°C +/- 2°C	PASS	-	IEC 60695-10-2
Thermal Conductivity	0.22	W/m.°C	ISO 8302
HDT, 0.45 MPa, 6.4 mm, unannealed	210	°C	ASTM D648
HDT, 1.82 MPa, 6.4 mm, unannealed	201	°C	ASTM D648
HDT, 0.45 MPa, 3.2 mm, unannealed	207	°C	ASTM D648
HDT, 1.82 MPa, 3.2mm, unannealed	190	°C	ASTM D648
Vicat Softening Temp, Rate B/50	211	°C	ASTM D1525
CTE, -20°C to 150°C, flow	5.2E-05	1/°C	ASTM E831
CTE, -20°C to 150°C, xflow	5.2E-05	1/°C	ASTM E831
Thermal Conductivity	0.22	W/m.°C	ASTM C177
Relative Temp Index, Elec ⁽²⁾	170	°C	UL 746B
Relative Temp Index, Mech w/impact ⁽²⁾	170	°C	UL 746B
Relative Temp Index, Mech w/o impact ⁽²⁾	170	°C	UL 746B
PHYSICAL ⁽¹⁾			
Density	1.27	g/cm ³	ISO 1183
Moisture Absorption, (23°C/50% RH/24hrs)	0.2	%	ISO 62-4
Moisture Absorption, (23°C/50% RH/Equilibrium)	0.7	%	ISO 62-4
Water Absorption, (23°C/24hrs)	0.25	%	ISO 62-1
Water Absorption, (23°C/saturated)	1.25	%	ISO 62-1
Melt Volume Rate, MVR at 360°C/5.0 kg	25	cm ³ /10 min	ISO 1133
Melt Volume Rate, MVR at 340°C/5.0 kg	13	cm ³ /10 min	ISO 1133
Specific Gravity	1.27	-	ASTM D792

PROPERTIES	TYPICAL VALUES	UNITS	TEST METHODS
Water Absorption, (23°C/24hrs)	0.25	%	ASTM D570
Water Absorption, (23°C/Saturated)	1.25	%	ASTM D570
Melt Flow Rate, 337°C/6.6 kgf	17.8	g/10 min	ASTM D1238
Poisson's Ratio	0.36	-	ASTM E132
Mold Shrinkage, flow, 3.2 mm ⁽³⁾	0.5 – 0.7	%	SABIC method
Mold Shrinkage, xflow, 3.2 mm ⁽³⁾	0.5 – 0.7	%	SABIC method
ELECTRICAL ⁽¹⁾			
Volume Resistivity	1.E+15	Ω.cm	IEC 60093
Surface Resistivity, ROA	>1.E+15	Ω	IEC 60093
Dielectric Strength, in oil, 0.8 mm	33	kV/mm	IEC 60243-1
Dielectric Strength, in oil, 1.6 mm	25	kV/mm	IEC 60243-1
Dielectric Strength, in oil, 3.2 mm	16	kV/mm	IEC 60243-1
Relative Permittivity, 1 MHz	2.9	-	IEC 60250
Dissipation Factor, 1 MHz	0.006	-	IEC 60250
Relative Permittivity, 50/60 Hz	2.9	-	IEC 60250
Dissipation Factor, 50/60 Hz	0.0005	-	IEC 60250
Dielectric Constant ⁽⁴⁾			
at 1.1 GHz	3.01	-	-
at 5 GHz	3.02	-	-
at 10 GHz	3.02	-	-
Dissipation Factor ⁽⁴⁾			
at 1.1 GHz	0.0012	-	-
at 5 GHz	0.0024	-	-
at 10 GHz	0.0027	-	-
Comparative Tracking Index	150	V	IEC 60112
Comparative Tracking Index, M	100	V	IEC 60112
Volume Resistivity	1.E+17	Ω.cm	ASTM D257
Dielectric Strength, in air, 1.6 mm	32.7	kV/mm	ASTM D149
Dielectric Strength, in oil, 1.6 mm	28.0	kV/mm	ASTM D149
Dielectric Strength, in oil, 3.2 mm	19.7	kV/mm	ASTM D149
Relative Permittivity, 100 Hz	3.15	-	ASTM D150
Dissipation Factor, 100 Hz	0.0015	-	ASTM D150
Relative Permittivity, 1 kHz	3.15	-	ASTM D150
Dissipation Factor, 1 kHz	0.0012	-	ASTM D150
Comparative Tracking Index (UL) {PLC} ⁽²⁾	4	PLC Code	UL 746A
Hot-Wire Ignition (HWI), PLC 1 ⁽²⁾	≥3	mm	UL 746A
Hot-Wire Ignition (HWI), PLC 2 ⁽²⁾	≥1.5	mm	UL 746A
High Amp Arc Ignition (HAI), PLC 3 ⁽²⁾	≥3	mm	UL 746A
High Amp Arc Ignition (HAI), PLC 4 ⁽²⁾	≥1.5	mm	UL 746A
High Voltage Arc Track Rate {PLC} ⁽²⁾	4	PLC Code	UL 746A
Arc Resistance, Tungsten {PLC} ⁽²⁾	5	PLC Code	ASTM D495
FLAME CHARACTERISTICS ⁽²⁾			
UL Yellow Card Link	E207780-100221357	-	-
UL Recognized, 94-5VA Flame Class Rating	≥3	mm	UL 94
UL Recognized, 94V-0 Flame Class Rating	≥1.5	mm	UL 94

PROPERTIES	TYPICAL VALUES	UNITS	TEST METHODS
Oxygen Index (LOI)	44	%	ASTM D2863
Oxygen Index (LOI)	47	%	ISO 4589
NBS Smoke Density, Flaming, Ds 4 min	2	-	ASTM E662
INJECTION MOLDING ⁽⁵⁾			
Drying Temperature	150	°C	
Drying Time	4 – 6	Hrs	
Drying Time (Cumulative)	24	Hrs	
Maximum Moisture Content	0.02	%	
Melt Temperature	350 – 410	°C	
Nozzle Temperature	345 – 405	°C	
Front - Zone 3 Temperature	345 – 415	°C	
Middle - Zone 2 Temperature	340 – 405	°C	
Rear - Zone 1 Temperature	330 – 400	°C	
Mold Temperature	135 – 180	°C	
Back Pressure	0.3 – 0.7	MPa	
Screw speed (Circumferential speed)	0.2 – 0.3	m/s	
Shot to Cylinder Size	40 – 60	%	
Vent Depth	0.025 – 0.076	mm	
EXTRUSION BLOW MOLDING			
Drying Temperature	140 – 150	°C	
Drying Time	4 – 6	Hrs	
Drying Time (Cumulative)	24	Hrs	
Maximum Moisture Content	0.01 – 0.02	%	
Melt Temperature (Parison)	320 – 355	°C	
Barrel - Zone 1 Temperature	325 – 350	°C	
Barrel - Zone 2 Temperature	330 – 355	°C	
Barrel - Zone 3 Temperature	330 – 355	°C	
Barrel - Zone 4 Temperature	330 – 355	°C	
Adapter - Zone 5 Temperature	330 – 355	°C	
Head - Zone 6 - Top Temperature	330 – 355	°C	
Head - Zone 7 - Bottom Temperature	330 – 355	°C	
Screw Speed	10 – 70	rpm	
Mold Temperature	65 – 175	°C	
Die Temperature	325 – 355	°C	

- (1) The information stated on Technical Datasheets should be used as indicative only for material selection purposes and not be utilized as specification or used for part or tool design.
- (2) UL Ratings shown on the technical datasheet might not cover the full range of thicknesses and colors. For details, please see the UL Yellow Card.
- (3) Measurements made from laboratory test coupon. Actual shrinkage may vary outside of range due to differences in processing conditions, equipment, part geometry and tool design. It is recommended that mold shrinkage studies be performed with surrogate or legacy tooling prior to cutting tools for new molded article.
- (4) Based on SPDR testing technique on dry as molded specimens.
- (5) Injection Molding parameters are only mentioned as general guidelines. These may not apply or may need adjustment in specific situations such as low shot sizes, large part molding, thin wall molding and gas-assist molding.

ADDITIONAL PRODUCT NOTES

No PFAS intentionally added: The grade listed in this document does not contain PFAS intentionally added during Seller's manufacturing process and is not expected to contain unintentional PFAS impurities. Each user is responsible for evaluating the presence of unintentional PFAS impurities.



MORE INFORMATION

For curve data and CAE cards, please visit and register at <https://materialfinder.sabic-specialties.com>

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